

### **DS25BR204**

# 3.125 Gbps 1:4 LVDS Repeater with Transmit Pre-Emphasis and Receive Equalization

### **General Description**

The DS25BR204 is a 3.125 Gbps 1:4 LVDS repeater optimized for high-speed signal routing and switching over lossy FR-4 printed circuit board backplanes and balanced cables. Fully differential signal paths ensure exceptional signal integrity and noise immunity.

The device has two different LVDS input channels and a select line determines which input is active. Both inputs have programmable equalization providing maximum signal strength. A loss-of-signal ( $\overline{LOS}$ ) circuit monitors both input channels and a unique  $\overline{LOS}$  pin reports when no signal is detected at that input.

Wide input common mode range allows the switch to accept signals with LVDS, CML and LVPECL levels; the output levels are LVDS. A very small package footprint requires a minimal space on the board while the flow-through pinout allows easy board layout. Each differential input and output is internally terminated with a  $100\Omega$  resistor to lower device return losses, reduce component count and further minimize board space.

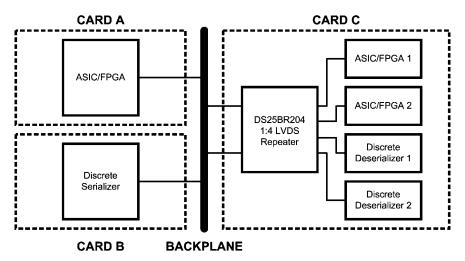
#### **Features**

- DC 3.125 Gbps low jitter, low skew, low power operation
- Pin selectable transmit pre-emphasis and receive equalization eliminate data dependant jitter
- Wide Input Common Mode Range allows DC-coupled interface to LVDS, CML and LVPECL drivers
- Redundant inputs
- Integrated  $100\Omega$  input and output terminations
- 8 kV ESD on LVDS I/O pins protects adjoining components
- Small 6 mm x 6 mm LLP-40 space saving package

#### **Applications**

- Clock and data distribution
- Clock and data buffering and muxing
- OC-48 / STM-16
- SD/HD/3GHD SDI Routers

### **Typical Application**

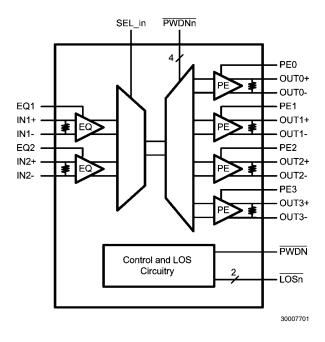


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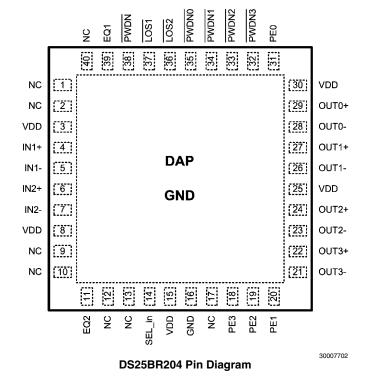
## **Ordering Code**

NSID	Function	Available Equalization Levels	Available Pre-Emphasis Levels
DS25BR204TSQ	1:4 Repeater	Off / On	Off / On

### **Block Diagram**



### **Connection Diagram**



# **Pin Descriptions**

Pin Name	Pin	I/O, Type	Pin Description
	Number		·
IN1+, IN1-,	4, 5,	I, LVDS	Inverting and non-inverting high speed LVDS input pins.
IN2+, IN2-,	6, 7,		
OUT0+, OUT0-,	29, 28,	O, LVDS	Inverting and non-inverting high speed LVDS output pins.
OUT1+, OUT1-,	27, 26,		
OUT2+, OUT2-,	24, 23,		
OUT3+, OUT3-	22, 21		
EQ1, EQ2,	39,11	I, LVCMOS	Receive equalization level select pins.
PE0, PE1,	31, 20,	I, LVCMOS	Transmit pre-emphasis level select pins.
PE2, PE3	19, 18		
SEL_in	14	I, LVCMOS	Input select pin.
LOS2	36,	O, LVCMOS	Loss of Signal output pin, LOSn, reports when an open input fault
LOS1	37		condition is detected at the input, INn. These are open drain
			outputs. External pull up resistors are required.
PWDN0,	35,	I, LVCMOS	Channel output power down pins. When the PWDNn is set to L,
PWDN1,	34,		the channel output, OUTn, is in the power down mode.
PWDN2,	33,		
PWDN3	32		
NC	1, 2,	NC	NO CONNECT pins. May be left floating.
	9, 10,		
	12, 13,		
	17, 40		
PWDN	38	I, LVCMOS	Device power down pin. When the PWDN is set to L, the device
			is in the power down mode.
VDD	3, 8,	Power	Power supply pins.
	15,25, 30		
GND	16, DAP	Power	Ground pin and a pad (DAP - die attach pad).

#### **Absolute Maximum Ratings** (Note 4)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage -0.3V to +4V-0.3V to  $(V_{CC} + 0.3V)$ LVCMOS Input Voltage LVCMOS Output Voltage -0.3V to  $(V_{CC} + 0.3V)$ -0.3V to +4V LVDS Input Voltage 0.0V to +1V LVDS Differential Input Voltage LVDS Output Voltage -0.3V to  $(V_{CC} + 0.3V)$ LVDS Differential Output Voltage 0.0V to +1V LVDS Output Short Circuit Current 5 ms Duration Junction Temperature +150°C Storage Temperature Range -65°C to +150°C Lead Temperature Range

Soldering (4 sec.) +260°C
Maximum Package Power Dissipation at 25°C

SQA Package 4.65W
Derate SQA Package 37.2 mW/°C above +25°C

Package Thermal Resistance

 $\begin{array}{ll} \theta_{JA} & +26.9^{\circ}\text{C/W} \\ \theta_{JC} & +3.8^{\circ}\text{C/W} \\ \text{ESD Susceptibility} \\ \text{HBM (Note 1)} & \geq 8 \text{ kV} \end{array}$ 

MM (Note 2) ≥250V CDM (Note 3) ≥1250V

Note 1: Human Body Model, applicable std. JESD22-A114C
Note 2: Machine Model, applicable std. JESD22-A115-A
Note 3: Field Induced Charge Device Model, applicable std.
JESD22-C101-C

# Recommended Operating Conditions

	Min	Тур	Max	Units
Supply Voltage (V <sub>CC</sub> )	3.0	3.3	3.6	V
Receiver Differential Input Voltage (V <sub>ID</sub> )	0		1	V
Operating Free Air Temperature (T <sub>A</sub> )	-40	+25	+85	°C

#### **Electrical Characteristics**

Over recommended operating supply and temperature ranges unless otherwise specified. (Notes 6, 7, 10)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
LVCMOS	DC SPECIFICATIONS	•				
V <sub>IH</sub>	High Level Input Voltage		2.0		$V_{DD}$	V
V <sub>IL</sub>	Low Level Input Voltage		GND		0.8	V
I <sub>IH</sub>	High Level Input Current	$V_{IN} = 3.6V$ $V_{CC} = 3.6V$		0	±10	μA
I <sub>IL</sub>	Low Level Input Current	$V_{IN} = GND$ $V_{CC} = 3.6V$		0	±10	μА
V <sub>CL</sub>	Input Clamp Voltage	$I_{CL} = -18 \text{ mA}, V_{CC} = 0V$		-0.9	-1.5	V
V <sub>OL</sub>	Low Level Output Voltage	I <sub>OL</sub> = 4 mA			0.4	V
	PUT DC SPECIFICATIONS					
V <sub>ID</sub>	Input Differential Voltage		0		1	V
V <sub>TH</sub>	Differential Input High Threshold	$V_{CM} = +0.05V \text{ or } V_{CC} -0.05V$		0	+100	mV
V <sub>TL</sub>	Differential Input Low Threshold		-100	0		mV
V <sub>CMR</sub>	Common Mode Voltage Range	V <sub>ID</sub> = 100 mV	0.05		V <sub>CC</sub> - 0.05	V
I <sub>IN</sub>	Input Current	$V_{IN} = 3.6V \text{ or } 0V$ $V_{CC} = 3.6V \text{ or } 0V$		±1	±10	μА
C <sub>IN</sub>	Input Capacitance	Any LVDS Input Pin to GND		1.7		pF
R <sub>IN</sub>	Input Termination Resistor	Between IN+ and IN-		100		Ω

Symbol	Parameter	Conditions	Min	Тур	Max	Units	
LVDS O	UTPUT DC SPECIFICATIONS			•			
V <sub>OD</sub>	Differential Output Voltage		250	350	450	mV	
ΔV <sub>OD</sub>	Change in Magnitude of V <sub>OD</sub> for Complimentary Output States	$R_L = 100\Omega$	-35		35	mV	
V <sub>os</sub>	Offset Voltage		1.05	1.2	1.375	V	
ΔV <sub>OS</sub>	Change in Magnitude of V <sub>OS</sub> for Complimentary Output States	$R_L = 100\Omega$	-35		35	mV	
I <sub>os</sub>	Output Short Circuit Current (Note 8)	OUT to GND		-35	-55	mA	
		OUT to V <sub>CC</sub>		7	55	mA	
C <sub>OUT</sub>	Output Capacitance	Any LVDS Output Pin to GND		1.2		pF	
R <sub>OUT</sub>	Output Termination Resistor	Between OUT+ and OUT-		100		Ω	
SUPPLY CURRENT							
I <sub>cc</sub>	Supply Current	PE = OFF, EQ = OFF, PWDN = H		150	185	mA	
I <sub>CCZ</sub>	Power Down Supply Current	PWDN = L		47	65	mA	

**Note 4:** "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditions at which the device is functional and the device should not be operated beyond such conditions.

**Note 5:** The Electrical Characteristics tables list guaranteed specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not guaranteed.

**Note 6:** Current into device pins is defined as positive. Current out of device pins is defined as negative. All voltages are referenced to ground except  $V_{OD}$  and  $\Delta V_{OD}$ .

Note 7: Typical values represent most likely parametric norms for  $V_{CC} = +3.3V$  and  $T_A = +25^{\circ}C$ , and at the Recommended Operation Conditions at the time of product characterization and are not guaranteed.

Note 8: Output short circuit current (I<sub>OS</sub>) is specified as magnitude only, minus sign indicates direction only.

## **AC Electrical Characteristics**

Over recommended operating supply and temperature ranges unless otherwise specified. (Notes 9, 10)

Symbol	Parameter	Cond	litions	Min	Тур	Max	Units
LVDS OUTPUT	F AC SPECIFICATIONS						
t <sub>PLHD</sub>	Differential Propagation Delay Low to High (Note 11)	$-R_1 = 100\Omega$			460	600	ps
t <sub>PHLD</sub>	Differential Propagation Delay High to Low (Note 11)	- 10052			420	600	ps
t <sub>SKD1</sub>	Pulse Skew It <sub>PLHD</sub> – t <sub>PHLD</sub> I (Notes 10, 12)				40	100	ps
t <sub>SKD2</sub>	Channel to Channel Skew (Notes 13, 11)				55	110	ps
t <sub>SKD3</sub>	Part to Part Skew (Notes 11, 14)				50	190	ps
t <sub>LHT</sub>	Rise Time (Note 11)	D = 1000			80	160	ps
t <sub>HLT</sub>	Fall Time (Note 11)	$R_L = 100\Omega$			80	160	ps
t <sub>ON</sub>	Any PWDN to Output Active Time				8	20	μs
t <sub>OFF</sub>	Any PWDN to Output Inactive Time				5	12	ns
t <sub>SEL</sub>	Select Time				5	12	ns
	DRMANCE WITH EQ = Off, PE = Off(Note	11) (Figure 5)					
t <sub>RJ1</sub>	Random Jitter (RMS Value)	V <sub>ID</sub> = 350 mV	2.5 Gbps		0.5	1	ps
t <sub>RJ2</sub>	No Test Channels (Note 15)	V <sub>CM</sub> = 1.2V Clock (RZ)	3.125 Gbps		0.5	1	ps
t <sub>DJ1</sub>	Deterministic Jitter (Peak to Peak)	V <sub>ID</sub> = 350 mV	2.5 Gbps		11	19	ps
t <sub>DJ2</sub>	No Test Channels (Note 16)	V <sub>CM</sub> = 1.2V K28.5 (NRZ)	3.125 Gbps		13	24	ps
t <sub>TJ1</sub>	Total Jitter (Peak to Peak)	V <sub>ID</sub> = 350 mV	2.5 Gbps		0.05	0.10	UI <sub>P-P</sub>
t <sub>TJ2</sub>	No Test Channels (Note 17)	V <sub>CM</sub> = 1.2V PRBS-23 (NRZ)	3.125 Gbps		0.07	0.13	UI <sub>P-P</sub>
JITTER PERFO	DRMANCE WITH EQ = Off, PE = On (Note	11)(Figure 6 Figure	9				
t <sub>RJ1B</sub>	Random Jitter (RMS Value)	V <sub>ID</sub> = 350 mV	2.5 Gbps		0.5	1	ps
t <sub>RJ2B</sub>	Test Channel B (Note 15)	V <sub>CM</sub> = 1.2V Clock (RZ)	3.125 Gbps		0.5	1	ps
t <sub>DJ1B</sub>	Deterministic Jitter (Peak to Peak)	V <sub>ID</sub> = 350 mV	2.5 Gbps		10	23	ps
t <sub>DJ2B</sub>	Test Channel B (Note 16)	V <sub>CM</sub> = 1.2V K28.5 (NRZ)	3.125 Gbps		4	20	ps
t <sub>TJ1B</sub>	Total Jitter (Peak to Peak)	V <sub>ID</sub> = 350 mV	2.5 Gbps		0.06	0.10	UI <sub>P-P</sub>
t <sub>TJ2B</sub>	Test Channel B (Note 17)	V <sub>CM</sub> = 1.2V PRBS-23 (NRZ)	3.125 Gbps		0.05	0.13	UI <sub>P-P</sub>
JITTER PERFO	DRMANCE WITH EQ = On, PE = Off (Note	11)(Figure 7 Figure	9)				
t <sub>RJ1D</sub>	Random Jitter (RMS Value)	V <sub>ID</sub> = 350 mV	2.5 Gbps		0.5	1	ps
t <sub>RJ2D</sub>	Test Channel D (Note 15)	V <sub>CM</sub> = 1.2V Clock (RZ)	3.125 Gbps		0.5	1	ps
t <sub>DJ1D</sub>	Deterministic Jitter (Peak to Peak)	V <sub>ID</sub> = 350 mV	2.5 Gbps		17	30	ps
t <sub>DJ2D</sub>	Test Channel D (Note 16)	V <sub>CM</sub> = 1.2V K28.5 (NRZ)	3.125 Gbps		15	28	ps
t <sub>TJ1D</sub>	Total Jitter (Peak to Peak)	V <sub>ID</sub> = 350 mV	2.5 Gbps		0.07	0.13	UI <sub>P-P</sub>
t <sub>TJ2D</sub>	Test Channel D (Note 17)	V <sub>CM</sub> = 1.2V PRBS-23 (NRZ)	3.125 Gbps		0.08	0.15	UI <sub>P-P</sub>

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Symbol	Parameter	Cond	Conditions		Тур	Max	Units		
JITTER PERFO	JITTER PERFORMANCE WITH EQ = On, PE = On (Note 11)(Figure 8 Figure 9								
t <sub>RJ1BD</sub>	Random Jitter (RMS Value)	V <sub>ID</sub> = 350 mV	2.5 Gbps		0.5	1	ps		
t <sub>RJ2BD</sub>	Input Test Channel D Output Test Channel B (Note 15)	V <sub>CM</sub> = 1.2V Clock (RZ)	3.125 Gbps		0.5	1	ps		
t <sub>DJ1BD</sub>	Deterministic Jitter (Peak to Peak)	V <sub>ID</sub> = 350 mV	2.5 Gbps		10	20	ps		
t <sub>DJ2BD</sub>	Input Test Channel D Output Test Channel B (Note 16)	V <sub>CM</sub> = 1.2V K28.5 (NRZ)	3.125 Gbps		8	21	ps		
t <sub>TJ1BD</sub>	Total Jitter (Peak to Peak)	V <sub>ID</sub> = 350 mV	2.5 Gbps		0.07	0.12	UI <sub>P-P</sub>		
t <sub>TJ2BD</sub>	Input Test Channel D Output Test Channel B (Note 17)	V <sub>CM</sub> = 1.2V PRBS-23 (NRZ)	3.125 Gbps		0.08	0.15	UI <sub>P-P</sub>		

**Note 9:** The Electrical Characteristics tables list guaranteed specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not guaranteed.

Note 10: Typical values represent most likely parametric norms for  $V_{CC} = +3.3V$  and  $T_A = +25^{\circ}C$ , and at the Recommended Operation Conditions at the time of product characterization and are not guaranteed.

 $\textbf{Note 11:} \ \textbf{Specification is guaranteed by characterization and is not tested in production}.$ 

Note 12: t<sub>SKD1</sub>, lt<sub>PLHD</sub> – t<sub>PHLD</sub>|, Pulse Skew, is the magnitude difference in differential propagation delay time between the positive going edge and the negative going edge of the same channel.

Note 13: t<sub>SKD2</sub>, Channel to Channel Skew, is the difference in propagation delay (t<sub>PLHD</sub> or t<sub>PHLD</sub>) among all output channels in Broadcast mode (any one input to all outputs).

Note 14:  $t_{SKD3}$ , Part to Part Skew, is defined as the difference between the minimum and maximum differential propagation delays. This specification applies to devices at the same  $V_{CC}$  and within 5°C of each other within the operating temperature range.

Note 15: Measured on a clock edge with a histogram and an acummulation of 1500 histogram hits. Input stimulus jitter is subtracted geometrically.

Note 16: Tested with a combination of the 1100000101 (K28.5+ character) and 0011111010 (K28.5- character) patterns. Input stimulus jitter is subtracted algebraically.

Note 17: Measured on an eye diagram with a histogram and an acummulation of 3500 histogram hits. Input stimulus jitter is subtracted.

### **DC Test Circuits**

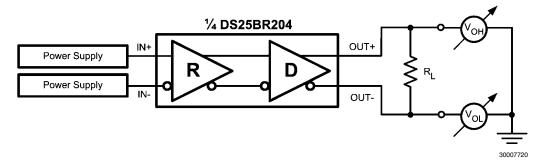


FIGURE 1. Differential Driver DC Test Circuit

# **AC Test Circuits and Timing Diagrams**

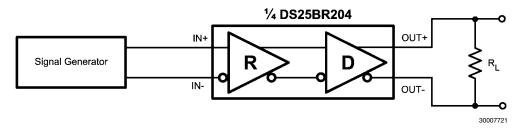


FIGURE 2. Differential Driver AC Test Circuit

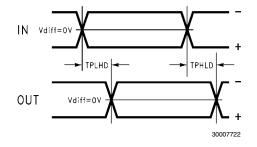
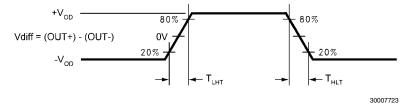
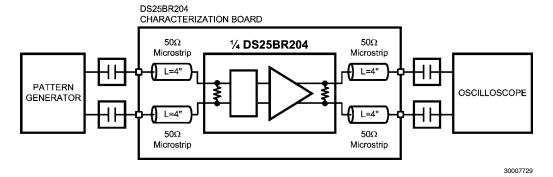


FIGURE 3. Propagation Delay Timing Diagram



**FIGURE 4. LVDS Output Transition Times** 

## **Pre-Emphasis and Equalization Test Circuits**



**FIGURE 5. Jitter Performance Test Circuit** 

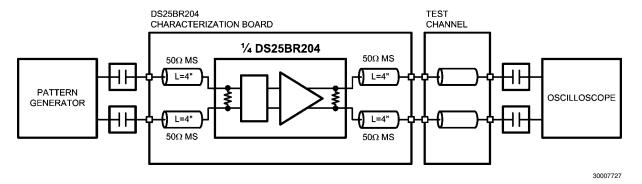


FIGURE 6. Pre-emphasis Performance Test Circuit

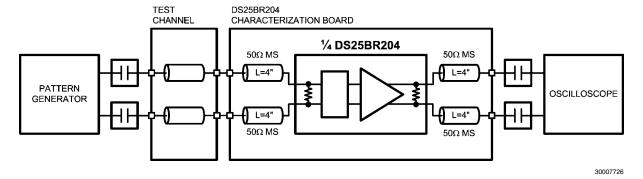


FIGURE 7. Equalization Performance Test Circuit

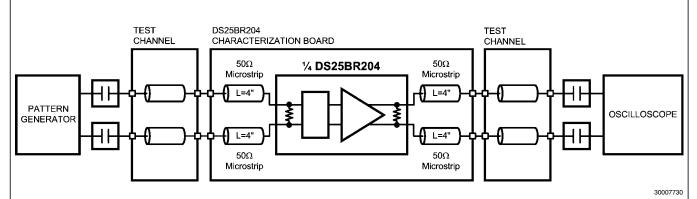


FIGURE 8. Pre-emphasis and Equalization Performance Test Circuit

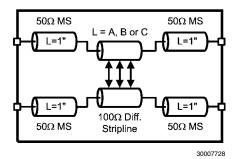


FIGURE 9. Test Channel Block Diagram

#### **Test Channel Loss Characteristics**

The test channel was fabricated with Polyclad PCL-FR-370-Laminate/PCL-FRP-370 Prepreg materials (Dielectric constant of 3.7 and Loss Tangent of 0.02). The edge coupled differential striplines have the following geometries: Trace Width (W) = 5 mils, Gap (S) = 5 mils, Height (B) = 16 mils.

Test Channel	Length		Insertion Loss (dB)				
	(inches)	500 MHz	750 MHz	1000 MHz	1250 MHz	1500 MHz	1560 MHz
Α	10	-1.2	-1.7	-2.0	-2.4	-2.7	-2.8
В	20	-2.6	-3.5	-4.1	-4.8	-5.5	-5.6
С	30	-4.3	-5.7	-7.0	-8.2	-9.4	-9.7
D	15	-1.6	-2.2	-2.7	-3.2	-3.7	-3.8
E	30	-3.4	-4.5	-5.6	-6.6	-7.7	-7.9
F	60	-7.8	-10.3	-12.4	-14.5	-16.6	-17.0

## **Functional Description**

The DS25BR204 is a 3.125 Gbps 1:4 LVDS repeater optimized for high-speed signal routing and switching over lossy FR-4 printed circuit board backplanes and balanced cables.

The DS25BR204 SEL\_in pin selects one out of two available LVDS inputs. The following is the input select truth tables.

### **Input Select Truth Table**

CONTROL Pin (SEL_in) State	Input Selected	
0	IN1	
1	IN2	

The DS25BR204 has a pre-emphasis control pin for each output for switching the transmit pre-emphasis to ON and OFF setting and an equalization control pin for each input for

switching the receive equalization to ON and OFF setting. The following are the transmit pre-emphasis and receive equalization truth tables.

### **Transmit Pre-Emphasis Truth Table**

OUTPUT OUTn, n = {0, 1, 2, 3}				
CONTROL Pin (PEn) State	Pre-emphasis Level			
0	OFF			
1	ON			

Transmit Pre-emphasis Level Selection for an Output OUTn

### **Receive Equalization Truth Table**

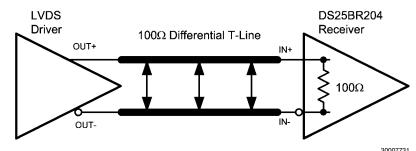
INPUT INn, n = {1, 2}				
CONTROL Pin (EQn) State	Equalization Level			
0	OFF			
1	ON			

Receive Equalization Level Selection for an Input INn

### Input Interfacing

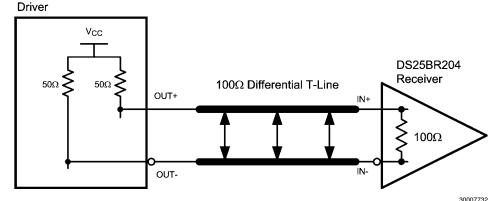
The DS25BR204 accepts differential signals and allows simple AC or DC coupling. With a wide common mode range, the DS25BR204 can be DC-coupled with all common differential

drivers (i.e. LVPECL, LVDS, CML). The following three figures illustrate typical DC-coupled interface to common differential drivers. Note that the DS25BR204 inputs are internally terminated with a  $100\Omega$  resistor.

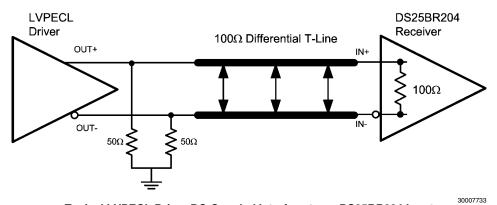


Typical LVDS Driver DC-Coupled Interface to an DS25BR204 Input

CML3.3V or CML2.5V



Typical CML Driver DC-Coupled Interface to an DS25BR204 Input

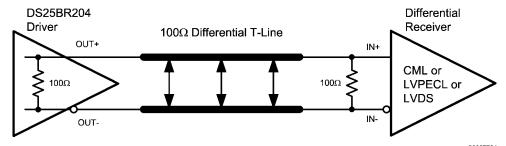


Typical LVPECL Driver DC-Coupled Interface to an DS25BR204 Input

### **Output Interfacing**

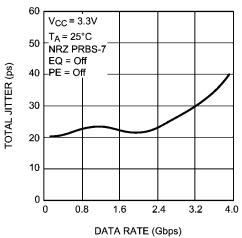
The DS25BR204 outputs signals compliant to the LVDS standard. Its outputs can be DC-coupled to most common differential receivers. The following figure illustrates typical DC-coupled interface to common differential receivers and

assumes that the receivers have high impedance inputs. While most differential receivers have a common mode input range that can accomodate LVDS compliant signals, it is recommended to check respective receiver's data sheet prior to implementing the suggested interface implementation.

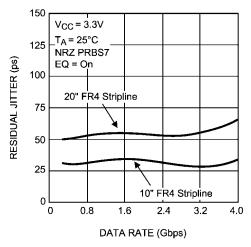


Typical DS25BR204 Output DC-Coupled Interface to an LVDS, CML or LVPECL Receiver

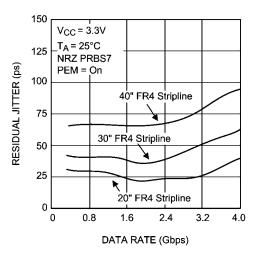
### **Typical Performance**



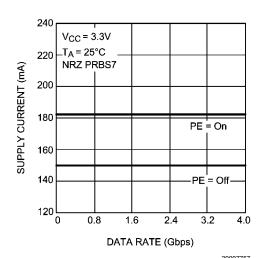
Total Jitter as a Function of Data Rate



Residual Jitter as a Function of Data Rate, FR4 Stripline Length and EQ Level

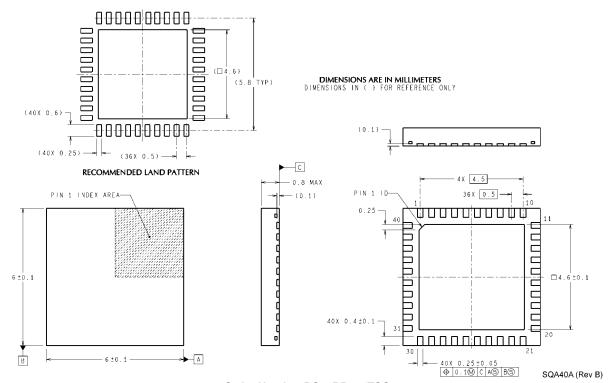


Residual Jitter as a Function of Data Rate, FR4 Stripline Length and PE Level



Supply Current as a Function of Data Rate and PE Level

## Physical Dimensions inches (millimeters) unless otherwise noted



Order Number DS25BR204TSQ
NS Package Number SQA40A
(See AN-1187 for PCB Design and Assembly Recommendations)

#### **Notes**

For more National Semiconductor product information and proven design tools, visit the following Web sites at:

Pr	oducts	De	sign Support
Amplifiers	www.national.com/amplifiers	WEBENCH	www.national.com/webench
Audio	www.national.com/audio	Analog University	www.national.com/AU
Clock Conditioners	www.national.com/timing	App Notes	www.national.com/appnotes
Data Converters	www.national.com/adc	Distributors	www.national.com/contacts
Displays	www.national.com/displays	Green Compliance	www.national.com/quality/green
Ethernet	www.national.com/ethernet	Packaging	www.national.com/packaging
Interface	www.national.com/interface	Quality and Reliability	www.national.com/quality
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